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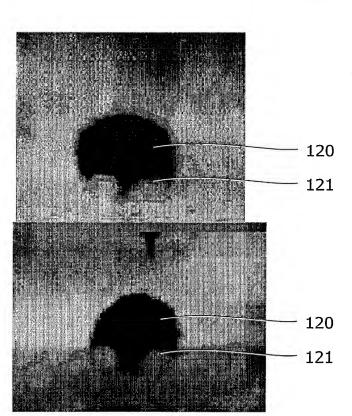
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(54) Title: OPTICAL MASTER SUBSTRATE AND METHOD TO MANUFACTURE HIGH-DENSITY RELIEF STRUCTURE



(57) Abstract: The invention relates to a master substrate, a method for making a highdensity relief structure, and optical discs replicated with the high-density relief structure, the master substrate comprising a substrate layer (10) and a recording stack deposited on the substrate layer, the recording stack comprising: - an information layer (12), - an interface layer (11) sandwiched between said information layer and the substrate, said information layer (12) comprising a growth-dominated phase-change material for forming marks and spaces representing an encoded data pattern, wherein said recording material is an alloy comprising at least two materials of the group of materials containing Ge, Sb, Te, In, Se, Bi, Ag, Ga, Sn, Pb, As. A very high-density relief structure is achieved.

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